

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A method of manufacturing an electronic part comprising a conductor film, a lower conductor layer, and an insulating member sandwiched between the conductor film and the lower conductor layer, for connecting the conductor film and the lower conductor layer by conductor portions and growing metal plating on the conductor portions and the conductor film, the method comprising:

forming a plurality of opening holes, each having said lower conductor layer as bottoms, through the conductor film and the insulating member from said conductor film side; [[,]]

growing metal plating layers, as conductor portions from each of the bottoms of said opening holes, from said lower conductor layer as an electrode; and [[,]]

growing the metal plating layers on [[the]] upper surfaces of said conductor film and said conductor portions with said conductor film and said conductor portions as electrodes after said conductor portions are formed in the respective plurality of opening holes by growing said metal plating layers so as to contact said metal plating layers with said conductor film, and to increase area for growing said metal plating layers and reduce current density per unit in said metal plating layers, so as to lower growing speed of said metal plating layers, to thereby form said conductor portions in said opening holes, and forming a thickness enough to form an upper conductor layer, wherein

the metal plating layers are grown from each of the bottoms of said opening holes, and on the upper surfaces of said conductor film and said conduction portions, without electroless plating being carried out.

Claim 2 (Currently Amended): A method of manufacturing an electronic part in which on ~~[[the]]~~ an upper surface of an insulating member covering a lower conductor layer, conductor portions connected from said lower conductor layer are exposed, the method comprising:

forming a conductor film on the upper surface of said insulating member and protective film formed on a part of the upper surface of said insulating member and protective film in a thickness direction, and thereafter forming a plurality of opening holes of which bottom is formed by said lower conductor layer, through said protective film and said conductor film; ~~[[,]]~~

growing metal plating layers, as said conductor portions from the bottoms of said plurality of opening holes with said lower conductor layer as an electrode; ~~[[,]]~~ and

growing the metal plating on ~~[[the]]~~ upper surfaces of said conductor film and said conductor portions with said exposed conductor film and said conductor portions on which protective film is not formed as electrodes, to thereby form a thickness enough to form an upper conductor layer after said conductor portions are formed to the substantial same height in the respective plurality of opening holes by growing said metal plating layers so as to contact said metal plating layers with said conductor film, and to increase area for growing said metal plating layers and reduce current density per unit in said metal plating layers, so as to lower growing speed of said metal plating layers, to thereby form said conductor portions in said opening holes, wherein

the metal plating layers are grown from each of the bottoms of said opening holes, and on the upper surfaces of said conductor film and said conduction portions, without electroless plating being carried out.

Claim 3 (Previously Presented): A method according to Claim 1, wherein said exposed conductor film providing said electrode is set outside a product area.

Claim 4 (Previously Presented): A method according to Claim 1, wherein said insulating member and said conductor film are made integral with each other in advance.

Claim 5 (Previously Presented): A method according to Claim 2, wherein said exposed conductor film providing said electrode is set outside a product area.

Claim 6 (Previously Presented): A method according to Claim 2, wherein said insulating member and said conductor film are made integral with each other in advance.